LN350GPH

Square Type

 \square 5.0 mm \times 5.0 mm

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol Rating | | Unit | |
|-------------------------------|------------------|-------------|------|--|
| Power dissipation | P_{D} | 90 | mW | |
| Forward current | I_{F} | 30 | mA | |
| Pulse forward current * | I_{FP} | 150 | mA | |
| Reverse voltage | V_R | 4 | V | |
| Operating ambient temperature | T _{opr} | -25 to +85 | °C | |
| Storage temperature | T _{stg} | -30 to +100 | °C | |

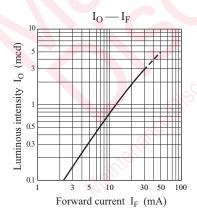
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

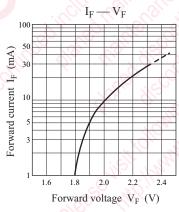
■ Lighting Color

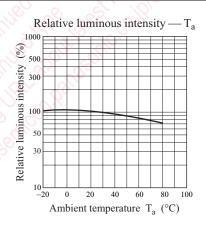
• Yellow Green

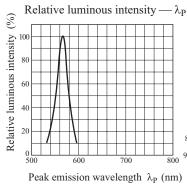
■ Electro-Optical Characteristics $T_a = 25$ °C

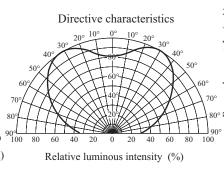
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--------------------------|------------------|-----------------------|------|-----|-----|------|
| Luminous intensity | I_{O} | 100 | 0.75 | 2.0 | | mcd |
| Reverse current | I_R | $V_R = 4 V$ | | | 10 | μΑ |
| Forward voltage | V _F | $I_F = 20 \text{ mA}$ | | 2.2 | 2.8 | V |
| Peak emission wavelength | $\lambda_{ m P}$ | $I_F = 20 \text{ mA}$ | 60 | 565 | 10, | nm |
| Spectral half band width | Δλ | $I_F = 20 \text{ mA}$ | 5 | 30 | 20 | nm |

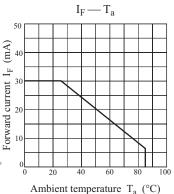










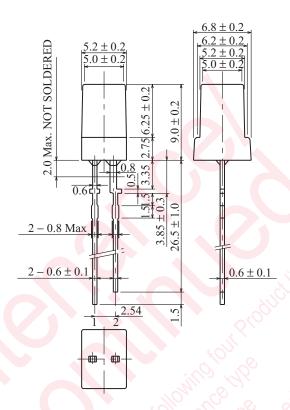


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LN350GPH Panasonic

■ Package (Unit: mm)

LLXFTN2SF500



- Pin name
 - 1: Anode
- 2: Cathode

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